MM1 – ESMini[™] COM with Intel[®] Atom[™]

- Intel[®] Atom™ Z530 or Z510, up to 1.6 GHz
- Up to 1 GB DDR2 SDRAM
- 1 PCI Express[®]
- Up to 2 Fast Ethernet interfaces
- 8 USB 2.0 (1 client)
- 2 UARTs
- Up to 2 CAN bus interfaces
- SDVO, LVDS
- Intel[®] HD Audio
- -40°C to +85°C Tcase screened (-25°C to +85°C Tcase with 1 GB DRAM)
- Conduction cooling



The MM1 is an ultra-small Computer-On-Module of the rugged ESMini[™] family. Together with an application-specific carrier board it forms a semicustom solution for industrial, harsh, mobile and mission-critical environments.

The MM1 is controlled by the Intel[®] Atom[™] processor, a first generation IA-32 core based on 45nm process technology. Due to the new power architecture of the Intel[®] Atom[™] CPU, the MM1 has a total power consumption of max. 5 to 10 W, while having a clock frequency of up to 1.6 GHz.

The MM1 accommodates up to 1 GB of directly soldered main memory and supports other memory like USB Flash on the carrier board.

The MM1 offers a multitude of I/O: besides modern serial I/O like one PCI Express[®] x1 link, LVDS, SDVO, high-definition audio, SATA and USB, it also provides legacy I/O (2 CAN, 2 COM, 2 Fast Ethernet, 2 I2C) and up to 120 FPGA signals.

The MM1 is completed by a board management controller for temperature and power supervision. It

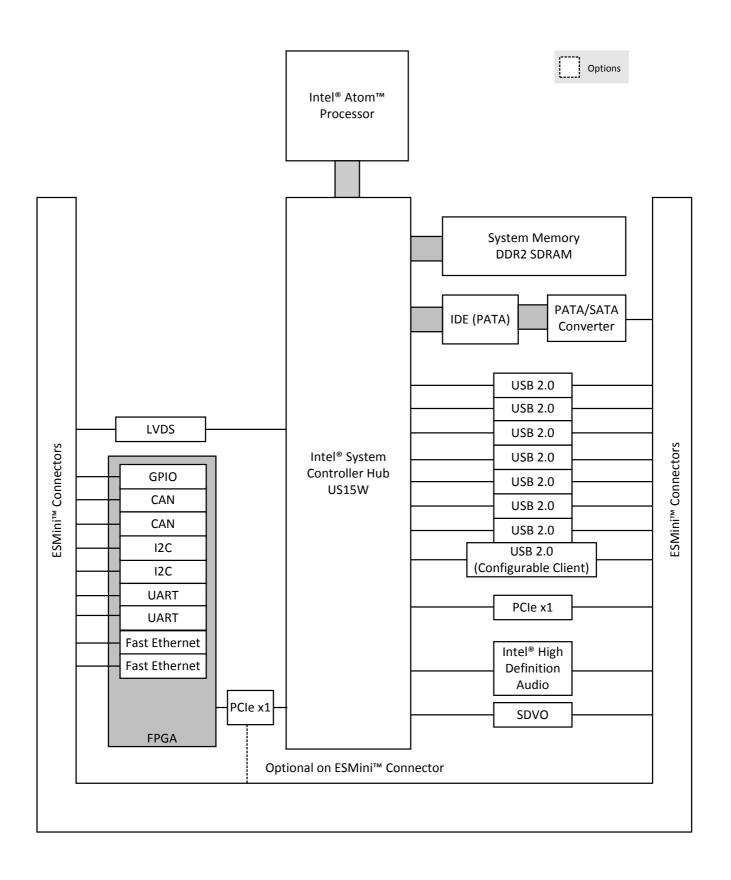
comes with a Phoenix[®] Award BIOS configurable for the final application.

The MM1 is screened for operation in a -40°C to +85°C temperature range (Tcase, -25°C to +85°C for board versions with 1 GB DRAM). As all ESMiniTM modules it is embedded in a covered frame. This ensures EMC protection and allows efficient conductive cooling. Air cooling is also possible by applying a heat sink on top of the cover. Where operation temperatures are moderate, the module may even do without the frame and cover, with a suitable low-power processor and airflow. ESMiniTM modules are firmly screwed to a carrier board and come with rugged industry-proven connectors supporting high frequency and differential signals. Only soldered components are used to withstand shock and vibration, and the design is optimized for conformal coating. The MM1 supports a 95x55mm form factor.

For evaluation and development purposes a microATX carrier board is available.



Diagram



Technical Data

CPU	 Intel[®] Atom[™] Z530 or Z510 Up to 1.6 GHz processor core frequency 400 MHz or 533 MHz system bus frequency Chipset Intel[®] system controller hub US15W
Memory	 512 KB L2 cache integrated in Atom processor Up to 1 GB DDR2 SDRAM system memory Soldered 400/533 MHz memory bus frequency locked to the FSB frequency
Serial ATA (SATA)	 One port via ESMini[™] connector Transfer rates up to 100 MB/s Via PATA-to-SATA converter
Graphics	 Integrated in Intel® System Controller Hub US15W Maximum resolution: 1366x768 pixels 1 SDVO port 1 LVDS port 112 MHz maximum pixel clock 18 or 24 bits pixel color depths Available via ESMini™ connector
USB	 Eight USB 2.0 host ports (or 7 host ports and 1 client port, adjustable by software) Via ESMini[™] connector Six of these ports also support USB 1.1 (UHCI implementation) EHCI implementation Data rates up to 480 Mbit/s
Ethernet	 Up to two 10/100Base-T Ethernet channels Two status LEDs per channel Available via ESMini™ connector
UART	 Two interfaces RS232 or RS422/RS485 Full or half-duplex Data rates up to 115,200 bit/s 60-byte transmit/receive buffer Handshake lines: RTS, CTS Available via ESMini[™] connector
CAN bus	 Two CAN bus channels 2.0 A/B CAN protocol Data rates up to 1 Mbit/s Available via ESMini™ connector
I ² C Bus	 Two interfaces Available via ESMini[™] connector
PCI Express®	 One x1 link to connect legacy I/O (FPGA) One x1 link via ESMini[™] connector Data rate 250 MB/s in each direction (2.5 Gbit/s per lane)
GPIO	 One line from board controller on ESMini[™] connector J1 Three lines from FPGA on ESMini[™] connector J1 Up to 19 differential pairs of receive and transmit lines on ESMini[™] connector J2 Up to 116 single I/O lines on ESMini[™] connector J2
HD Audio	■ Via ESMini [™] connector

Technical Data

Board Management Controller	 Input voltage supervision Power sequencing Board monitoring Watchdog Accessible via SMBus 	
Miscellaneous	 Real-time clock (with Goldcap or battery backup on the carrier board) SMBus interface 	
Electrical Specifications	 Supply voltage: +5V (-3%/+5%) Power consumption: 1.1 GHz Z510 model: 6.75 W typ., 7.7 W max. 1.6 GHz Z530 model: 7.5 W typ., 9.3 W max. 	
Mechanical Specifications	 Dimensions: 95 mm x 55 mm ESMini[™] PCB mounted between a frame and a cover Weight: 130 g (with cover and frame) 	
Environmental Specifications	 Temperature range (operation): -40+85°C Tcase (ESMini[™] cover/frame) (screened) (board versions with 512 MB DDR2 SDRAM) -25+85°C Tcase (ESMini[™] cover/frame) (screened) (board versions with 1 GB DDR2 SDRAM) Temperature range (storage): -40+85°C Relative humidity (operation): max. 95% non-condensing Relative humidity (storage): max. 95% non-condensing Altitude: -300 m to + 3,000 m Shock: 15 g/11 ms (EN 60068-2-27) Bump: 10 g/16 ms (EN 60068-2-29) Vibration (sinusoidal): 1 g/10150 Hz (EN 60068-2-6) Conformal coating on request 	
MTBF	221,026 h @ 40°C according to IEC/TR 62380 (RDF 2000)	
Safety	PCB manufactured with a flammability rating of 94V-0 by UL recognized manufacturers	
EMC	EMC behavior depends on the system and housing surrounding the ESMini [™] module. MEN has performed general, successful EMC tests for ESMini [™] using the XC4 evaluation carrier according to EN 55022 (radio disturbance), IEC 61000-4-2 (ESD), IEC 61000-4-3 (electromagnetic field immunity), IEC 61000-4-4 (burst), IEC 61000-4-5 (surge) and IEC 61000-4-6 (conducted disturbances)	
BIOS	Award BIOS	
Software Support	 Windows[®] Windows[®] XP Windows[®] Vista[™] Windows[®] 7 Windows[®] XP Embedded Windows[®] Embedded Standard 7 Linux (in preparation) VxWorks[®] (on request) QNX[®] (on request) For more information on supported operating system versions and drivers see Downloads. 	

Configuration & Options

Standard Configurations

Article No.	СРИ Туре	Clock	System RAM	Ethernet	CAN	ESMini Connectors	Operating Temperature
15MM01-00	Z510	1.1 GHz	512 MB	1	1	J1	-40+85°C Tcase screened
15MM01-01	Z530	1.6 GHz	1 GB	2	2	J1, J2	-25+85°C Tcase screened

Options

СРИ	 Intel[®] Atom[™] Z530, 1.6 GHz Intel[®] Atom[™] Z510, 1.1 GHz
Memory	 System RAM 512 MB or 1 GB
I/O	Second Fast Ethernet portSecond CAN port
PCI Express®	 Second PCI Express[®] lane on ESMini[™] connector Instead of FPGA (GPIO, CAN, UART, Fast Ethernet, I²C)
Operating Temperature	 -40+85°C Tcase (ESMini[™] cover/frame) (screened) (board versions with 512 MB DDR2 SDRAM) -25+85°C Tcase (ESMini[™] cover/frame) (screened) (board versions with 1 GB DDR2 SDRAM)
Cooling	 With cover and frame With cooling plate With small heat sinks only on processor and chipset
BIOS	 Accessible via UART using VT100 terminal
Software Support	 VxWorks[®] (on request) QNX[®] (on request)

Please note that some of these options may only be available for large volumes. Please ask our sales staff for more information.

Ordering Information

Standard MM1 Models	15MM01-00	Intel [®] Atom™ Z510, 1.1 GHz, 512MB RAM, 1 Fast Ethernet, 1 CAN, -40+85°C Tcase screened
	15MM01-01	Intel [®] Atom™ Z530, 1.6 GHz, 1GB RAM, 2 Fast Ethernet, 2 CAN, -25+85°C Tcase screened
Related Hardware	08XC04-00	Evaluation and development board for all ESMini™ modules, 0+60°C, incl. 2 GB USB Flash Disk and SA-Adapters™ for 1 RS232 and 1 CAN bus
	08XC06-01	Carrier board for ESMini™: 1x TTY, 1x RS232, 1x DVI-I, 1x Audio I/O, 4x USB2.0, 2x Fast Ethernet, USB Flash slot, PCI Express® Mini Card socket, SIM card holder, microSD™ card socket, 8x GPIOs, -40°C+85°C screened
Miscellaneous Accessories	0712-0019	Standard ATX PSU, 350 W, 0+40°C
	08XC04-00	Evaluation and development board for all ESMini™ modules, 0+60°C, incl. 2 GB USB Flash Disk and SA-Adapters™ for 1 RS232 and 1 CAN bus
	08XC06-01	Carrier board for ESMini [™] : 1x TTY, 1x RS232, 1x DVI-I, 1x Audio I/O, 4x USB2.0, 2x Fast Ethernet, USB Flash slot, PCI Express [®] Mini Card socket, SIM card holder, microSD [™] card socket, 8x GPIOs, -40°C+85°C screened
Software: Linux	This product is designed to work under Linux. See below for potentially available separate software p from MEN.	
	13XM01-06	MDIS5™ low-level driver sources (MEN) for XM1, XM1L, MM1, MM2, XM2, F11S, F19P, F21P, F22P, G20, G22, SC21, SC27 and DC2 board controller
	13Z015-06	MDIS5™ low-level driver sources (MEN) for 16Z029_CAN (MSCAN/Layer2)
	13Z016-06	MDIS5™ driver (MEN) for 16Z029_CAN (CANopen master)
	13Z017-06	MDIS5™ low-level driver sources (MEN) for 16Z034_GPIO, 16Z037_GPIO and 16Z127_GPIO
	13Z025-90	Linux native driver (MEN) for 16Z025_UART, 16Z057_UART and 16Z125_UART
	13Z077-90	Linux native driver (MEN) for 16Z077_ETH and 16Z087_ETH

Ordering Information

Software: Windows®	This product is designed to work under Windows [®] . See below for potentially available separate software packages from MEN.			
	10F014-78	Windows [®] XP Embedded BSP (MEN) for F11S, F14, F15, F17, F18, F19P, F21P, G20, XM1, XM1L, XM2, MM1, MM2, SC21, SC24, DC1, DC2, RC1, BC50I, BC50M and BL50W		
	10Y000-78	Windows [®] Embedded Standard 7 BSP for F11S, F19P, F21P, F22P, F75P, G20, G22, XM1L, XM2, MM1, MM2, SC21, SC24, SC27, BC50M, BC50I, BL50W, BL50S, DC13, F206, F210, F215, F216, G215, P506, P507 and P511		
	13MM01-77	Windows [®] Installset (MEN) for MM1 and RC1 (Includes all free drivers developed by MEN for the supported hardware.)		
	13T009-70	Windows® HD audio driver (Realtek) for XM1, XM1L, MM1, MM2		
	13T011-70	Windows [®] graphics driver (Intel [®]) for XM1, XM1L, MM1 and F11S		
	13T012-70	Windows® XP/Vista chipset driver (Intel®) for XM1, XM1L, MM1 and F11S		
	13T013-70	Windows® USB client driver installation package (Intel®) for XM1, XM1L and MM1		
	13T014-70	Windows® Vista™ HD audio driver (Realtek) for XM1, XM1L and MM1		
	13T016-70	Windows® Vista™ chipset graphics driver (Intel®) for XM1, XM1L, MM1 and F11S		
	13Z015-70	MDIS4™/2004 / MDIS5™ Windows [®] driver (MEN) for 16Z029_CAN (MSCAN/Layer2)		
	13Z016-70	MDIS5™ Windows [®] driver (MEN) for 16Z029_CAN (CANopen master)		
	13Z017-70	MDIS4™/2004 / MDIS5™ Windows [®] driver (MEN) for 16Z034_GPIO devices		
	13Z087-70	Windows® native driver (MEN) for 16Z087_ETH (Ethernet controller)		
Software: Firmware/BIOS	MEN's CANopen firmware consists of the Vector Informatik protocol stack. The corresponding driver software comes from MEN. It is based on MDIS [™] (MEN Driver Interface System), which makes the hardware ready for use under Windows [®] , Linux, VxWorks [®] , QNX [®] , OS-9 [®] and other software environments. You can find more information on the Vector CANopen tools at www.vector-informatik.de.			
Software: Miscellaneous	Intel® software development products such as analyzers, compilers, threading tools etc. can be downloaded under www.intel.com/cd/software/products/asmo-na/eng/index.htm. IA-32 Intel® Architecture Software Developer's Manuals are available under www.intel.com/products/processor/manuals/index.htm.			
For operating systems not mentioned here contact MEN sales.				
Documentation	Compare Chart ESMini [™] Computer-On-Modules » Download You can find general literature on MEN computer-on-modules, including presentations about ESMexpress ESMini [™] and their cooling concept, in our Download Library.			
	20APPN004	Application Note: How to make a USB stick bootable		
	20MM01-ER	MM1 Errata		
	20MM01-00	MM1 User Manual		
	21APPN016	Application Note: Accessing SMBus under Linux Kernel 3.2 on MEN Intel [®] Boards		
	ZIAIINOIO	Application Note: Necessing Simplify and er Einax Nerrer 5.2 on MER Inter Boards		

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